Atty, Dkt. No. AMAT/3577.X1/DSM/BCVD/JW

Padgett, M.

D STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Judy Huang

Serial No.: 09/336,525

Confirmation No.: 7748

Filed:

June 18, 1999

For:

Plasma Treatment to

Enhance Adhesion and to Minimize Oxidation of

Carbon-Containing Layers

BEST AVAILABLE COPY

Assistant Commissioner for Patents

Washington, D.C. 20231

Dear Sir:

CERTIFICATE OF MAILING 37 CFR 1.8

Group Art Unit: 1762

Examiner:

I hereby certify that this correspondence is being use June 17, 2002 with the United States Postal Service as Castal In an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.

RESPONSE TO OFFICE ACTION DATED MARCH 15, 2002

In response to the Office Action dated March 15, 2002, having a shortened statutory period for response set to expire on June 15, 2002, please enter the following amendments and reconsider the claims pending in the application for reasons discussed below.

IN THE CLAIMS:

Please amend the claims as follows:

24. A method of processing a semiconductor substrate, comprising:

depositing a first layer on the semiconductor substrate, the first layer comprising a material selected from the group consisting of organic polymeric materials, αC, αFC, SiCOH, and SiC;

exposing the first layer to a plasma consisting essentially of an inert gas; and depositing a second layer over the first layer.

The method of claim 24, wherein the first layer comprises silicon carbide. 25.